EPROM

X6

Capacity	Type No.	Organization	Max. Access Time (ns)	Max. Cycle Time (ns)	Power Supply	Operating Temperature (°C)	Max. Power Dissipation		No. of Pins	Process
							Active	Stand by		
1M Bit	TC5710001/AD-12	131.072 x 8	120	120	5V±5%	0 ~ 70	158	0.525	32	CMOS
	TC5710001AD-150		150	150	5V±10%		165	0.550		
	TC57H1000/1AD-85		85	85	5V±5%		210	0.525		
	TC57H1000/1AD-100		100	100	5V±10%		220	0.550		
	TC57H1024AD-85	65,536 x 16	85	85	5V±5%		315	0.525	40	
	TC57H0124AD-100		100	100	5V±10%		330	0.55		
	TC57H1025AD-55		55	55	5V±5%		473	105		
	TC57H1025AD-70		70	70						
4M Bit	TC574000AD-120	524,288 x 8	120	120	5V±10%	0 ~ 70	330	0.550	32	CMOS
	TC57400AD-150		150	150			275			
	TC574200D-10	524,288 x 8 262,144 x 16	100	100	5V±5%		368	0.525	40	
	TC574200D-120		120	120	5V±10%		330	0.550		
	TC574200D-150		150	150						
	TC574096D-10	262,144 x 16	100	100	5V±5%		368	0.525		
	TC574096D-120		120	120	5V±10%		330	0.550		
	TC574096D-150		150	150						
8M Bit	TC578200D-150	1,048,576 x 8 525,286 x 16	150	150	5V±10%	0 ~ 70	330	0.550	42	CMOS
	TC578200D-200		200	200						
16M Bit	TC5716200D-150	2,097,152 x 8 1,048,576 x 16	150	150	5V±10%	0 ~ 70	330	0.550	42	CMOS
	TC5716200D-200		200	200						

ONE TIME PROM

X6

Capacity	Type No.	Organization	Max. Access Time (ns)	Max. Cycle Time (ns)	Power Supply	Max. Power Dissipation		No. of Pins	Process
						Active	Stand by		
1M Bit	TC541000/1AP/AF-12	131,072 x 8	120	120	5V±5%	158	0.525	32	CMOS
	TC541000/1AP/AF-15		150	150					
	TC54H1000/1AP/AF-85		85	85		210			
	TC54H1000/1AP/AF-10		100	100					
	TC54H1024AP/AF-85	65,536 x 16	85	85		315		40	
	TC54H1024AP/AF-10		100	100					
4M Bit	TC544000AP/AF-12	524,288 x 8	120	120	5V±5%	315	0.525	32	CMOS
	TC544000AP/AF-150		150	150	5V±10%	275	0.550		
	TC544200P/F-120	524,288 x 8 262,144 x 16	120	120		330		40	
	TC544200P/F-150		150	150					

Package P: Plastic DIP F: Flat Package (SOP)